

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

TSSOP Exp. Pad

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TOTAL MASS (g) : 0.067478

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003455	1000000	51201.9414062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025576	975000	379027.71875		
		Iron (Fe)	7439-89-6	0.000630	24000	9336.38867188		
		Phosphorus (P)	7723-14-0	0.000008	300	118.557312012		
		Zinc (Zn)	7440-66-6	0.000018	700	266.753967285		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
Lead Frame Total:				0.026232	1000000	388749.4375		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002364	1000000	35032.3515625		
		External Plating Total:				0.002364	1000000	35032.3515625
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001030	1000000	15264.2548828		
Internal Plating Total:				0.001030	1000000	15264.2548828		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001019	750000	15101.2373047		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000340	250000	5038.68554688		
Die Attach Total:				0.001359	1000000	20139.9238281		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004875	150000	72245.8671875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.026650	820000	394944.0625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000813	25000	12048.3867188		
		Carbon Black (C)	1333-86-4	0.000163	5000	2415.60546875		
		Encapsulation Total:				0.032501	1000000	481653.9375
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000537	1000000	7958.15966797		
					TOTAL MASS (g) :	0.067478		